

矽基板上連接線之輻射分析

鄭大福、邱政男

E-mail: 9315045@mail.dyu.edu.tw

摘要

本論文主要是討論矽基板上傳輸線之輻射效應，首先解得傳輸線上之電壓、電流值，將傳輸線切成極小線段，藉由Silvester映像理論求得映像電流，採以電偶型式作輻射，得到在頻域下輻射場值的轉換函數，利用傅立葉轉換將時域下信號源轉至頻域，與轉換函數作合成，並觀察改變信號源上升、下降時間的輻射場值變化，這些結果可作為設計者於電磁相容、電磁干擾上之參考。

關鍵詞：輻射；傳輸線

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